

01/25/02

Docket No. ST01-006

A

Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: **IL KWON SHIM, HERMES T. APALE, WEDDIE AQUIEN, DARIO FILOTEO, VIRGIL ARARAO, LEO**

MERITO

Title: **HEAT SPREADER ANCHORING & GROUNDING METHOD & THERMALLY ENHANCED PBGA PACKAGE USING**

THE SAME

Enclosed are:

- ☒ 8 sheets of drawing(s) - formal.
- ☒ An assignment of the invention to **St Assembly Test Services Pte Ltd**
- ☐ An associate power of attorney ☐ Applicant claims small entity status
- ☐ Request & Certification under 35 USC 122 (b) (2) (b) (i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 740.
TOTAL CLAIMS	33 -20=	13	x 18 =	\$ 234.
INDEP CLAIMS	3 -3=	0	x 84 =	\$ 0.
MULTIPLE DEPENDENT CLAIM PRESENTED			+ 260 =	
			SUB TOTAL	\$ 974.
			ASSIGNMENT	\$40.
			TOTAL	\$ 1,014.

☒ Please charge my Deposit Account No. 19-0033 in the amount of \$ 1,014. A duplicate copy of this sheet is enclosed.

☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.

☒ Any additional filing fees required under 37 CFR \$1.16.

☒ Any patent application processing fees under 37 CFR \$1.17.

Respectfully submitted,

STEPHEN B. ACKERMAN, REG. NO. 37,761

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I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Washington, D.C. 20231. Applicant and/or Attorney requests the date of deposit as the Filing Date.

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